



19TH ASIA PACIFIC CONFERENCE ON CIRCUITS AND SYSTEMS (APCCAS 2023) & THE ASIA PACIFIC CONFERENCE ON POSTGRADUATE RESEARCH IN MICROELECTRONICS & ELECTRONICS (PRIME ASIA) DESIGN CONTEST

19-22 November 2023, Hyderabad, India

Co-Located with the Asia-Pacific Conference on Postgraduate Research in Microelectronics and Electronics (PRIME Asia 2023)

Theme: Safe, Secure, Smart Circuits & Systems for a Sustainable Society

CALL FOR FPGA GRAND CHALLENGE

APCCAS 2023 and PRIME Asia 2023 is holding an International Design Contest to provide a platform to showcase innovative hardware and software solutions to real-world problems.

THEME OF THE CONTEST

The theme of the Design Contest is aligned with the conference theme of 'Safe, Secure, Smart Circuits and Systems for a Sustainable Society'. It is expected to involve a hardware / software co-designed solution using an FPGA, making use of hardware acceleration. You will be showcasing design approaches and solutions in the areas / domains of AI/ML, IoT, Industrial Automation, Automotive, Healthcare, Environment, Clean Energy, etc.

HARDWARE PLATFORM

The hardware platform to be used is Microchip Technology's RISC-V based PolarFire SoC. This will be made available to the shortlisted teams.

ELIGIBILITY

Participants should be bona fide undergraduate or postgraduate (including PhD) students in a discipline of interest to the IEEE. A team can have mentors who are not students, but the lead author(s) and presenter(s) should be students.

PRIZES

Prizes will be announced at a later stage.

IMPORTANT DATES

ACCEPTANCE NOTIFICATION	7 Aug 2023
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ACKNOWLEDGEMENT OF CONFERENCE PARTICIPATION	15 Aug 2023
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STAGE-1 : IDEA SUBMISSION

Your idea submission should cover:

- Your team details along with your contact information and postal address.
- A summary as well as a detailed description of the idea along with a block diagram.
- Benefits and value addition of your solution, application scenarios.

STEPS FOR SUBMISSION

1. Download template available on the conference website.
2. Fill all required details as required.
3. Submit a pdf version following the instructions available on the conference website.

Following the first round of screening, shortlisted teams will convert their ideas into applications / solutions using the PolarFire SoC Icycle Kit. Hardware kits will be shipped to the selected teams.

STAGE-2 : IMPLEMENTATION

Implementation should be on the Microchip Technology PolarFire SoC Icycle Kit provided.

Training materials and support will be provided for this platform.

PUBLICATION IN PRIME ASIA

Participants shortlisted for Stage-2 are invited to submit their work as IEEE PRIME Asia papers selecting the special session "Student Design Contest". The papers will be regularly reviewed and, if accepted, must be presented at IEEE PRIME Asia 2023

IDEA SUBMISSION	31 July 2023
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HARDWARE KIT DISTRIBUTION	16 Aug 2023
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PRESENTATION	19-22 Nov 2023
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Contact: apccas2023designcontest@gmail.com